PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Ming-Tse Lin	01/18/2013
Chu-Fu Lin	01/18/2013
Chien-Li Kuo	01/18/2013
Yung-Chang Lin	01/18/2013

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13747492

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER:	NAUP1561USA
NAME OF SUBMITTER:	SIBYL YU

Total Attachments: 8 source=1558921#page1.tif source=1558921#page2.tif

PATENT REEL: 029673 FRAME: 0555 13747492

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PATENT REEL: 029673 FRAME: 0556

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

Chip With Through Silicon Via Electrode And Method Of Forming The Same

As the below named inventor, I here This declaration is directed to:	by declare that:			
☑ The attached application, or				
☐ United States application nu	ımber	file	ed on	, or
☐ PCT international applicatio	n number		filed on	
The above-identified application was	made or authorized	d to be made by r	ne.	
I believe that I am the original invent application.	or or an original join	t inventor of a cla	imed invention ir	n the
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr				e
In consideration of the payment by	UNITED MICRO	ELECTRONIC	\$ having a po	ostal address of
No.3, Li-Hsin Road 2, Science	-Based Industria	al Park, Hsin-C	Chu City 300,	Гаiwan, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an			the receipt of wh	ich is hereby
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified applica invention by the above application or substitutes, or extensions thereof, ar	nd to any and all imp tion and, in and to, a r any continuations,	provements which all Letters Patent continuation-in-pa	n are disclosed in to be obtained fo art, divisions, ren	the or said ewals,
I hereby covenant that no assignmer entered into which would conflict with		or encumbrance l	nas been or will b	oe made or
I further covenant that ASSIGNEE w and documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ition and said Letter estify as to the same	s Patent and lega in any interferen	al equivalents as ce, litigation proc	may be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have he	olication, said invent scessary or desirable	on and said Lette to carry out the	ers Patent and sa proposes thereof	aid f. (Date of signing)
Note: An application data sheet (PTC				_

Page 1 of 8

NPO#NAU-P1561-USA:0 CUST#UMCD-2012-0321

Inventor: Ming-Tse Lin Date: JAN 18 2013

Signature: Ming - Tse Lin

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NPO#NAU-PI561-USA:0 CUST#UMCD-2012-0321 F#NPO-P0002E-US1201 DSC0-101U014773

PATENT

REEL: 029673 FRAME: 0558

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

Chip With Through Silicon Via Electrode And Method Of Forming The Same

As the below named inventor, I here This declaration is directed to:	eby declare that:		
☑ The attached application, or	r		
☐ United States application nu	umber	_filed on	, or
☐ PCT international applicatio	n number	filed on	
The above-identified application was	s made or authorized to be made	by me.	
I believe that I am the original invent application.	or or an original joint inventor of a	a claimed invention in th	ne
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr			
In consideration of the payment by	UNITED MICROELECTRON CORP.	NICS having a posta	al address of
No.3, Li-Hsin Road 2, Science	e-Based Industrial Park, Hs	in-Chu City 300, Ta	iwan, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar		00), the receipt of which	is hereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all improvements w ution and, in and to, all Letters Pat r any continuations, continuation-	hich are disclosed in the tent to be obtained for s in-part, divisions, renew	e aid ⁄als,
I hereby covenant that no assignmer entered into which would conflict with		nce has been or will be	made or
I further covenant that ASSIGNEE wand documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ntion and said Letters Patent and estify as to the same in any interfe	legal equivalents as ma erence, litigation proceed	y be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WINTNESS WHEREOF, I have h	olication, said invention and said lecessary or desirable to carry out	_etters Patent and said the proposes thereof.	Date of signing)
Note: An application data sheet (PT0 inventive entity, must accompany thi			٠.

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NPO#NAU-P1561-USA:0 CUST#UMCD-2012-0321

LEGAL NAME OF INVENTOR(ASSIGNOR)						
Inventor:	Chu-Fu Lin		Date:	JAN	1 8 2013	
Signature:	Chu-Fu	Sin				

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NPO#NAU-P1561-USA:0 CUST#UMCD-2012-0321 F#NPO-P0002E-US1201 DSC0-101U014773

PATENT

REEL: 029673 FRAME: 0560

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

Chip With Through Silicon Via Electrode And Method Of Forming The Same

As the below named inventor, I hereb This declaration is directed to:	y declare that:			
☑ The attached application, or				
☐ United States application nu	mber	filed o	on	, or
☐ PCT international application	number	file	d on	
The above-identified application was	made or authorized to l	oe made by me.		
I believe that I am the original invento application.	or or an original joint inv	entor of a claime	d invention in	the
I hereby acknowledge that any willful under18 U.S.C. 1001 by fine or impris				•
	UNITED MICROELE CORP.	ECTRONICS	having a pos	stal address of
No.3, Li-Hsin Road 2, Science-	Based Industrial P	ark, Hsin-Chu	City 300, T	aiwan, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good and	I of the sum of One Do d valuable consideration	llar (\$ 1.00), the 1.	receipt of whic	ch is hereby
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified applicat invention by the above application or substitutes, or extensions thereof, and	d to any and all improve ion and, in and to, all Le any continuations, cont	ements which are etters Patent to b inuation-in-part,	e disclosed in e obtained for divisions, rene	the · said ewals,
I hereby covenant that no assignmen entered into which would conflict with		ncumbrance has	been or will be	e made or
I further covenant that ASSIGNEE wil and documents relating to said invent known and accessible to I and will tes related thereto and will promptly exec	ion and said Letters Pa stify as to the same in a	tent and legal ed ny interference, l	uivalents as n itigation proce	nay be
representatives any and all papers, in maintain, issue and enforce said appl equivalents thereof which may be ned IN WINTNESS WHEREOF, I have he	ication, said invention a cessary or desirable to	and said Letters F carry out the prop	Patent and sai	
Note: An application data sheet (PTO inventive entity, must accompany this				

Page 5 of 8

NPO#NAU-P1561-USA:0 CUST#UMCD-2012-0321

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Chien-Li Kuo

Date: JAN 18 2013

Signature: JAN 18 2013

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NPO#NAU-P1561-USA:0 CUST#UMCD-2012-0321 F#NPO-P0002E-US1201 DSC0-101U014773

PATENT REEL: 029673 FRAME: 0562

COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention:

Chip With Through Silicon Via Electrode And Method Of Forming The Same

As the below named inventor, I here This declaration is directed to:	eby declare that:			
☑ The attached application, or	r ·			
☐ United States application number			filed on	
☐ PCT international application	n number	file	d on	
The above-identified application was	s made or authorized to	be made by me.		
I believe that I am the original inventapplication.	tor or an original joint inv	entor of a claime	d invention in	ı the
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr				е
In consideration of the payment by	UNITED MICROELI	ECTRONICS	having a po	estal address of
No.3, Li-Hsin Road 2, Science	e-Based Industrial P	ark, Hsin-Chu	City 300, 1	Γaiwan, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good are			receipt of whi	ich is hereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified application of substitutes, or extensions thereof, and	nd to any and all improv ation and, in and to, all L r any continuations, con	ements which are etters Patent to b tinuation-in-part,	e disclosed in e obtained fo divisions, ren	the r said ewals,
I hereby covenant that no assignme entered into which would conflict wit		ncumbrance has	been or will b	e made or
I further covenant that ASSIGNEE wand documents relating to said inverknown and accessible to I and will to related thereto and will promptly exe	ntion and said Letters Pa estify as to the same in a	atent and legal ed any interference, l	juivalents as i	may be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be no IN WINTNESS WHEREOF, I have h	olication, said invention a ecessary or desirable to	and said Letters F carry out the prop	Patent and sa poses thereof	
Note: An application data sheet (PT)				

Page 7 of 8

LEGAL NAME OF INVENTOR(ASSIGNOR)

inventor:

Yung-Chang Lin

Date:

JAN 18 2013

Signature:

Ywo-chay fi

8 of 8

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F#NPO-P0002E-US1201 DSC0-101U014773

NPO#NAU-P1561-USA:0 CUST#UMCD-2012-0321

> PATENT REEL: 029673 FRAME: 0564

RECORDED: 01/23/2013